

Electronic Acknowledgement Receipt

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Application Number:	10802566
International Application Number:	
Confirmation Number:	3507
Title of Invention:	High performance IC chip having discrete decoupling capacitors attached to its IC surface
First Named Inventor/Applicant Name:	Mou-Shiung Lin
Customer Number:	89518
Filer:	Dennis Alan Duchene/Patricia Balero
Filer Authorized By:	Dennis Alan Duchene
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Application Type:	Utility under 35 USC 111(a)

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Submitted with Payment	yes
Payment Type	Deposit Account
Payment was successfully received in RAM	\$180
RAM confirmation Number	5981
Deposit Account	502624
Authorized User	
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)/ Message Digest	Multi Part /.zip	Pages (if appl.)
1	Information Disclosure Statement (IDS) Filed (5B/08)	InformationDisclosureState nt1-085027-0109.pdf	169672 9d9e618ef58d0c2d6d88f73ca2855ae118c5244ec	no	3
Warnings:					
Information:					
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2	NPL Documents	0557TW_Office_Action_10_08_2009_pdf.pdf	1506201 b279e4e88bae4811c4b278973a13881c0b628c6a38	no	12
Warnings:					
Information:					
3	Information Disclosure Statement (IDS) Filed (5B/08)	InformationDisclosureState nt2-085027-0109.pdf	186451 0d6c406a20f80c0420c7ba76a53349c995a0a2346	no	5
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4	NPL Documents	1_MISTRY_45nm_logic.pdf	2254221 072127b1241426487d48b36305577a0d079281092	no	4
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5	NPL Documents	2_EDELSTEIN_Advantages_of_Copper.pdf	3696109 d4aa37204b1d94203a708a279d61948f6c5506874	no	9
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Information:					
6	NPL Documents	3_THENG_An_automated_tool_deployment_for_ESD.pdf	4517666 1a3408cd7c761547370da4bca4129abc08aaac0b74	no	7
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7	NPL Documents	4_GAO_An_improved_electrostatic_discharge_protection_structure.pdf	885848 7805c75db4d5367a9064015e1853ca2a0779c885	no	6
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8	NPL Documents	5_YOEH_Copper_Die_Bumps.pdf	717153 6e09b2af6c3f93cd0c6b0946c641b4b118e0c0a	no	5
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9	NPL Documents	6_HU_Copper_Polyimide.pdf	436455 60f08bdc-c4880c3bc25da62121b117bc2-67a85	no	7
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10	NPL Documents	7_ROESCH_Cycling_Copper_Flip_Chip_Connects.pdf	1142794 8112031f74624273c3c041a4f79ac245e1578-d027	no	8
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11	NPL Documents	8_LEE_Effect_of_ESD_layout_on_the_assembly_yield.pdf	889090 a726022251815546292126de7bc2828505516014	no	4
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12	NPL Documents	9_YEOH_ESD_effects_on_power_supply_clamps.pdf	226994 db271bc6a48723a9886f9476e4dc5e195-ed8a65	no	4
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13	NPL Documents	10_EDELSTEIN_Full_copper_wiring.pdf	1205963 95d166db84-c389f18b1179f-ed0b26a7bc7b-14122	no	4
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16	NPL Documents	13_GROVES_HighQ_Inductors_in_a_SiGE_BICMOS_process.pdf	420788 8c2628a69459c3c4ed1d15ba58f7c4a315995-6a0c	no	4
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18	NPL Documents	15_KUMAR_Intel_ISSCC_2009_paper_on_power_on_chip.pdf	2528325 c3a0da080c311c1b191a5d602d1793b81c1f8	no	2
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25	NPL Documents	22_PDF_LUTHER_Planar_Copper_pdf.pdf	2095781 90af629bed75c8d46787563c763b959c1c20f876ca	no	8
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26	NPL Documents	23_PDF_MASTER_Ceramic_Ball_Grid_Array_pdf.pdf	1069512 bbf6eeea156a9013c17b776d18818a6d015ba0b	no	5
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27	NPL Documents	24_PDF_MALONEY_Stacked_P MOS_clamps_for_high_voltage _power_supply_protection_pd f_pdf.pdf	1327621 bf7254b30d1890a26269a1501436d32580c bdc68b	no	8
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28	NPL Documents	25_PDF_LIN_A_New_System_ On_Chip_Technology_pdf_pdf pdf	390082 4206653caca8f6518d866c58f77b9a151edfa 4296	no	7
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29	NPL Documents	26_PDF_MEGICA_Brochure_Jea flets_01_28_04_pdf_pdf.pdf	888383 aac8f84b56c7db17d31ee962144db85c181f 609a	no	3
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30	NPL Documents	27_PDF_LIN_Post_Passivation_ Technology_Presentation_for_ TSMC_Tech_Symposium_2003 __pdf.pdf	1277639 20556a2754a2807cc282bcc5d8702d4d527 17e89	no	32
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31	NPL Documents	28_PDF_LIN_A_New_IC_Interc onnection_Scheme_and_Design _pdf.pdf	116206 e1e1d8b65cd9007c73db6677a10a8e17106 ccc8b	no	4
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32	Fee Worksheet (PTO-875)	fee-info.pdf	30003 f7226de4734789c5870b1c6664d4db0ec57 564ed	no	2
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Total Files Size (in bytes):			42568302		

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New Applications Under 35 U.S.C. 111

If a new application is being filed and the application includes the necessary components for a filing date (see 37 CFR 1.53(b)-(d) and MPEP 506), a Filing Receipt (37 CFR 1.54) will be issued in due course and the date shown on this Acknowledgement Receipt will establish the filing date of the application.

National Stage of an International Application under 35 U.S.C. 371

If a timely submission to enter the national stage of an international application is compliant with the conditions of 35 U.S.C. 371 and other applicable requirements a Form PCT/DO/EO/903 indicating acceptance of the application as a national stage submission under 35 U.S.C. 371 will be issued in addition to the Filing Receipt, in due course.

New International Application Filed with the USPTO as a Receiving Office

If a new international application is being filed and the international application includes the necessary components for an international filing date (see PCT Article 11 and MPEP 1810), a Notification of the International Application Number and of the International Filing Date (Form PCT/RO/105) will be issued in due course, subject to prescriptions concerning national security, and the date shown on this Acknowledgement Receipt will establish the international filing date of the application.